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Attorney Docket No. 501.1066D00

To the Honorable Commissioner of Patents … ginal documents or copy thereof.

1. Name of conveying party(ies):

Hideki KIHARA
Minoru SORAOKA
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Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Hitachi High-Technologies Corporation
24-14, Nishishinbasi 1-chome
Minato-ku, Tokyo
JAPAN

113260 U.S. PTO
29/237008
082605

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: **August 1, 2005, August 3, 2005, August 3, 2005 and August 3, 2005**

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: **August 1, 2005, August 3, 2005, August 3, 2005 and August 3, 2005**.

A. Patent Application No.(s)

B. Patent Registration No.(s)

Additional number(s) attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **ANTONELLI, TERRY, STOUT & KRAUS, LLP**

Internal Address:

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City: **ARLINGTON** State: **VA** Zip **22209**

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41)………………… **$40.00**

☒ Enclosed

☒ Authorized to be charged to deposit account

8. Deposit account number:

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Melvin Kraus, Reg#22,466
Name of Person Signing

Signature

08/26/2005
Date

Total number of pages including cover sheet, attachments, and document: 2

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ASSIGNMENT
（譲 渡 証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation,
a corporation organized under the laws of Japan,
located at 24-14, Nishishinbashi 1-chome, Minato-ku, Tokyo, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said Hitachi High-Technologies Corporation,
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1)	Hideki Kihara	8/1/2005
2)	Minoru Soraoka	8/3/2005
3)	Yuuzou Oohirabaru	8/3/2005
4)	Nobuo Nagayasu	8/3/2005
5)		
6)		
7)		
8)		
9)		
10)		